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United States Patent [19]**Kondo et al.**[11] **Patent Number:** **5,304,389**[45] **Date of Patent:** **Apr. 19, 1994**[54] **NON-HYGROSCOPIC ICING
COMPOSITION**[75] **Inventors:** **Tsutomu Kondo, Kanagawa; Akio
Nishimura, Tokyo, both of Japan**[73] **Assignee:** **Mitsubishi Kasei Corporation,
Tokyo, Japan**[21] **Appl. No.:** **985,956**[22] **Filed:** **Dec. 4, 1992****Related U.S. Application Data**[63] **Continuation of Ser. No. 722,463, Jun. 27, 1991, aban-
doned.**[51] **Int. Cl.⁵ A23G 3/00**[52] **U.S. Cl. 426/659; 127/29;
426/572**[58] **Field of Search 426/572, 658, 660, 659;
127/30, 31, 72, 29**[56] **References Cited****U.S. PATENT DOCUMENTS**

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Primary Examiner—Jeanette Hunter**Attorney, Agent, or Firm**—Sughrue, Mion, Zinn,
Macpeak & Seas[57] **ABSTRACT**

A non-hygroscopic icing composition is disclosed. The icing comprises sugar, fat and an emulsifier as the main components, wherein 80% by weight or more of said sugar is particles passing through a 63 μ m mesh size sieve and 40% by weight or more of said sugar is particles having a size of from 32 μ m to 63 μ m and the sugar content in the icing is 50% by weight or more.

9 Claims, No Drawings